EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S156	2	(("5882956") or ("6007920")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2010/08/19 10:01
S157	59	(furukawa).as. laser dicing	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/19 10:03
S162	0	die adj dond$3 laser	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/19 10:26
S163	5094	die adj bond$3 laser	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/19 10:26
S164	575	die adj bond$3 laser same (adhesive) same (substrate or wafer or carrier)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/19 10:27
S165	7	die adj bond$3 laser same (adhesive) same (substrate or wafer or carrier) (laser near (first second))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/19 10:48
S166	16	("20040180473" | "20050242073" | "20060035411" | "20060205183" | "20060216911" | "20060255022" | "20060281226" | "20070004179" | "20070109526" | "20070128767" | "20070141811" | "20070264799" | "6130401" | "6514795" | "6896760" | "7388172").PN. OR ("7737002").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2010/08/19 10:53

S167	323	die adj bond$3 laser with (adhesive) laser with (substrate or wafer or carrier)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/19 11:09
S168	56	die adj bond$3 laser with (adhesive) same wavelength laser with (substrate or wafer or carrier) same wavelength	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/19 12:36
S169	29	die adj bond$3 laser with (adhesive) same energy laser with (substrate or wafer or carrier) same energy	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/19 13:19
S170	2	11/806847.app.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/24 11:47
S171	0	(55/977767).APP.	US-PGPUB; USPAT; USOCR	OR	OFF	2010/08/24 13:38
S172	1	("5597767").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2010/08/24 13:38
S173	1	("20070293021").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2010/08/26 13:59
S174	75	(US-20070224733-$ or US-20040113283-$ or US-20040048419-$ or US-20040104491-$ or US-20050070095-$ or US-20020098608-$ or US-20040002199-$ or US-20040137699-$ or US-20020100941-$ or US-20040097054-$ or US-20060128065-$ or US-20020177288-$ or US-20060094208-$ or US-20040180473-$ or US-20020137309-$ or US-20020055238-$ or US-20010000079-$ or US-20070293021-$ or US-20050242073-$ or US-20040026382-$ or US-20070249145-$).did. or (US-5641714-$ or US-6908784-$ or US-7482702-$ or US-6319754-$ or US-6589809-$ or US-7015064-$ or US-5597767-$ or	US-PGPUB; USPAT; JPO; DERWENT	AND	ON	2010/08/26 14:15

		US-7192843-$ or US-6964915-$ or US-7413929-$ or US-6930392-$ or US-7063765-$ or US-7029950-$ or US-6972215-$ or US-6677183-$ or US-6873059-$ or US-7122447-$ or US-6943094-$ or US-6896760-$ or US-6514795-$ or US-6413839-$ or US-6861285-$ or US-6734083-$ or US-5762744-$ or US-5110388-$ or US-6558975-$).did. or (US-7408259-$ or US-6919262-$ or US-6007920-$ or US-7235465-$ or US-6589818-$ or US-5882956-$ or US-5411921-$ or US-5927993-$ or US-6762074-$ or US-6780734-$ or US-6656819-$ or US-7737002-$ or US-6970612-$ or US-7275815-$ or US-7579260-$ or US-7696014-$).did. or (JP-2002343747-$ or JP-2007150206-$ or JP-2006128577-$ or JP-2003173988-$ or JP-2003163186-$).did. or (JP-2002343747-$ or JP-2007150206-$ or JP-2006186305-$ or JP-2006128577-$ or JP-2006093368-$ or JP-2003163186-$ or WO-2005004226-$).did.				
S175	16	S174 memory	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/26 14:15
S176	2	(("20070293021") or ("20050242073")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2010/08/26 14:19
S177	210	(wafer adj divid$3 method).ti.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/26 21:24
S178	168	(disco).as. (first near5 laser) (second near5 laser)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/26 21:33

S179	102	(disco).as. (first near2 laser) (second near2 laser)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/26 21:33
S180	106	(disco).as. (laser with adhesive) (laser with wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/26 21:33
S181	1	("20050009307").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2010/08/30 09:34
S182	85	first near laser second near laser (adhesive) with (cut$3 or dic$3 or scrib$3 or drill$3 or divid$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/30 09:36
S183	15	("20040002199" | "20050006728" | "20050082644" | "4729971" | "6117347" | "6211488" | "6399463" | "6562698" | "6849524" | "6992026" | "7008861" | "7129114" | "7169687" | "7265033").PN. OR ("7550367").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2010/08/30 09:56
S184	420	438/463,460,463,118.ccls. laser same adhesive	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/30 09:59
S185	727	438/463,460,463,118.ccls. laser (tape or adhesive) with (dic$3 or cut$4 or drill$3 or separat$3 or divid$3 or scrib$3 or singulat$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/30 10:01
S186	0	438/463,460,463,118.ccls. laser (tape or adhesive) with (dic$3 or cut$4 or drill$3 or separat$3 or divid$3 or scrib$3 or singulat$3) (wavlength pulse frquency) same laser	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/30 10:02
S187	0	438/463,460,463,118.ccls. laser (tape or adhesive) with (dic$3 or cut$4 or drill$3 or separat$3 or divid$3 or scrib$3 or singulat$3) (wavlength pulse frequency) same laser	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/30 10:02

S188	135	438/463,460,463,118.ccls. laser (tape or adhesive) with (dic$3 or cut$4 or drill$3 or separat$3 or divid$3 or scrib$3 or singulat$3) (wavelength pulse frequency) same laser	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/30 10:02
S189	16	("20040180473" | "20050242073" | "20060035411" | "20060205183" | "20060216911" | "20060255022" | "20060281226" | "20070004179" | "20070109526" | "20070128767" | "20070141811" | "20070264799" | "6130401" | "6514795" | "6896760" | "7388172").PN. OR ("7737002").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2010/08/30 11:09
S190	80	(US-20070224733-$ or US-20040113283-$ or US-20040048419-$ or US-20040104491-$ or US-20050070095-$ or US-20020098608-$ or US-20040002199-$ or US-20040137699-$ or US-20020100941-$ or US-20040097054-$ or US-20060128065-$ or US-20020177288-$ or US-20060094208-$ or US-20040180473-$ or US-20020137309-$ or US-20020055238-$ or US-20010000079-$ or US-20070293021-$ or US-20050242073-$ or US-20040026382-$ or US-20070249145-$ or US-20050009307-$ or US-20060040472-$).did. or (US-5641714-$ or US-6908784-$ or US-7482702-$ or US-6319754-$ or US-6589809-$ or US-7015064-$ or US-5597767-$ or US-7192843-$ or US-6964915-$ or US-7413929-$ or US-6930392-$ or US-7063765-$ or US-7029950-$ or US-6972215-$ or US-6677183-$ or US-6873059-$ or US-7122447-$ or US-6943094-$ or US-6896760-$ or US-6514795-$ or US-6413839-$ or US-6861285-$ or	US-PGPUB; USPAT; JPO; DERWENT	AND	ON	2010/08/31 08:45

		US-6734083-$ or US-5762744-$ or US-5110388-$ or US-6558975-$).did. or (US-7408259-$ or US-6919262-$ or US-6007920-$ or US-7235465-$ or US-6589818-$ or US-5882956-$ or US-5411921-$ or US-5927993-$ or US-6762074-$ or US-6780734-$ or US-6656819-$ or US-7737002-$ or US-6970612-$ or US-7275815-$ or US-7579260-$ or US-7696014-$).did. or (JP-2002343747-$ or JP-2007150206-$ or JP-2006128577-$ or JP-2003173988-$ or JP-2003163186-$ or JP-2004022936-$).did. or (JP-2002343747-$ or JP-2007150206-$ or JP-2006186305-$ or JP-2006128577-$ or JP-2006093368-$ or JP-2003163186-$ or WO-2005004226-$ or JP-61222703-$ or US-20040089644-$).did.				
S191	2662	257/E21.598,E21.599.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/31 08:53
S192	97	257/E21.598,E21.599.ccls. laser same (scrib$3 or groove or cut$4 or dicing or dice or diced or singulat$3 or divid$3 or separat$3) (wafer adhesive) with laser	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/31 08:54
S193	0	257/E21.598,E21.599.ccls. laser same (scrib$3 or groove or cut$4 or dicing or dice or diced or singulat$3 or divid$3 or separat$3 or machine or machining) (different) with laser with (conditions or characteristics or settings or parameters) with (adhesive wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/31 09:40

S194	0	257/E21.598,E21.599.ccls. laser same (scrib$3 or groove or cut$4 or dicing or dice or diced or singulat$3 or divid$3 or separat$3 or machine or machining) (different or select $3) with laser with (conditions or characteristics or settings or parameters) with (adhesive wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/31 09:41
S195	0	257/E21.598,E21.599.ccls. (different or select$3) with laser with (conditions or characteristics or settings or parameters) with (adhesive wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/31 09:41
S196	2	257/E21.598,E21.599.ccls. (different or select$3) with laser same (conditions or characteristics or settings or parameters) same (adhesive wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/31 09:42
S197	260	257/E21.598,E21.599.ccls. laser with (first second)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/31 09:43
S198	115	257/E21.598,E21.599.ccls. laser with (first second) adhesive	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/31 09:56
S199	21	257/E21.598,E21.599.ccls. laser near2 (machin$3 or cut$4 or dicing or diced or dice or scrib$3 or divid$3 or separat $3) near4 adhesive	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2010/08/31 10:21
S200	1	("20050009307").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2010/08/31 12:46

EAST Search History (Interference)

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8/31/2010 2:02:38 PM
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